What is claimed is:

1. An electromagnetic interference (EMI) suppression device for suppressing both common mode and differential mode noises, comprising:

a case;

a common mode noise reduction element accommodated in the case;

a plurality of conductive pillars, each penetrating through the case to form a connection pad; and

at least one differential mode noise reduction element fixed to the conductive pillar and electrically connected to the common mode noise reduction element; wherein

the EMI device is mounted onto a printed circuit board(PCB) via the connection pad.

2. The EMI suppression device as described in claim 1, wherein the common mode noise reduction element is a common mode choke.

3. The EMI suppression device as described in claim 1, wherein the differential mode noise reduction element is a ferrite bead.

4. The EMI suppression device as described in claim 1, wherein the case is made of plastic.

5. The EMI suppression device as described in claim 1, wherein the conductive pillars are made of metal.

6. The EMI suppression device as described in claim 1, wherein the differential mode noise reduction element is fixed to the conductive pillars by means of an adhesive.

7. The EMI suppression device as described in claim 1, wherein on the surface of the conductive pillar is formed with a notch.

8. An electromagnetic interference (EMI) suppression device for suppressing both common mode and differential mode noises, comprising:

a case having a housing and a plurality of foot portions protruding from the housing;

a common mode noise reduction element accommodated in the housing;

a plurality of conductive pillars, each penetrating through the case to form two separate portions, a mount and a connection pad; and

at least one differential mode noise reduction element fixed to the mounts of the conductive pillars and electrically connected to the common mode noise reduction element; wherein

the EMI device is mounted onto a PCB via the connection pads.

9. The EMI suppression device as described in claim 8, wherein the differential mode noise reduction element is fixed to the conductive pillars by means of an adhesive.

10. The EMI suppression device as described in claim 1, wherein on the surface of the conductive pillar is formed with a notch.